

# INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Attorney Docket Number	23-69853-01
Application Number	10/727,062
Filing Date	December 2, 2003
First Named Inventor	John G. DeSteele
Art Unit	1795
Examiner Name	Jeffrey Thomas Barton

## U.S. PATENT DOCUMENTS

Copies of U.S. Patent documents do not need to be provided, unless requested by the Patent and Trademark Office. For patents, provide the patent number and the issue date. For published U.S. applications, provide the publication number and the publication date. For unpublished pending patent applications, provide the application number and the filing date and submit a copy.

Examiner's Initials*	Cite No. (optional)	Number	Date	Name of Applicant or Patentee

## FOREIGN PATENT DOCUMENTS

Examiner's Initials*	Cite No. (optional)	Country	Number	Date	Name of Applicant or Patentee

Examiner's Initials*	Cite No. (optional)	OTHER DOCUMENTS
		<p>Bottner, H., "Thermoelectric Micro Devices: Current State, Recent Developments and Future Aspects for Technological Progress and Applications," <i>Proc. 21st Int. Conf. Thermoelectronics, Long Beach, CA</i>, pp. 511-518 (August 25-29, 2002).</p> <p>Final Office action from the U.S. Patent and Trademark Office for U.S. Patent Application No. 10/726,744, dated April 13, 2009.</p> <p>Kim, D.-H. et al., "Effect of deposition temperature on the structural and thermoelectric properties of bismuth telluride thin films grown by co-sputtering," <i>Thin Solid Films</i>, Vol. 510, pp. 148-153 (2006).</p> <p>Office action from the U.S. Patent and Trademark Office in U.S. Patent Application No. 10/581,281, dated April 30, 2009.</p> <p>Sun, C.W. et al., "Crystallization behavior of non-stoichiometric Ge-Bi-Te ternary phase change materials for PRAM application," <i>J. Phys. Condens. Matter</i>, Vol. 19, 446004, 9 pages (2007).</p>

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\* Examiner: Initial if reference considered, whether or not in conformance with MPEP 609. Draw line through cite if not in conformance and not considered. Include copy of this form with next communication to applicant.